

PRODUCTS

isola



LAMINATES & PRE-PREG ISOLA USA

- Isola FR-4 Epoxy
- Isola Lead Free
- Isola High Performance
 - Polyimide
 - Low / No Flow Prepreg
 - High Speed/Low Loss Laminates



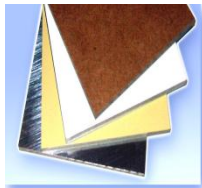
DRY FILM PHOTORESIST & SILVER ARTWORK FILM DUPONT

- Riston® Photoresist Dry Film
 - Inner Layer Dry Film
 - Outer Layer Dry Film
 - Specialty Dry Film
- Artwork Film – Silver/Diazo Film
- Developer Chemistry
- Dry Film Solder Mask



LAMINATION ASSIST MATERIALS CAC

- CAC® (Copper-Aluminum-Copper)
- Aluminum Foils for Drilling and Lamination Separators



BACK UP & ENTRY L.C.O.A.

- Entry:
 - Bullseye™
 - EO +
 - Solid Aluminum
- Back-up:
 - Slickback®
 - Spectrum Gold
 - STARboard
 - Tekboard



PROCESS CHEMISTRY FOCUS TECH

- Chemical Solutions for Printed Circuit Boards
- Customized Imaging Chemistries
- Process Control Hardware Solutions
- Develop/Etch/Strip and Strip/Etch/Strip
- Cleaners, Antifoam, Microetch

RELEASE FILMS & LAMINATION PADS PACOTHANE



- Pacothane Release Materials
- Pacopad Press Pads
- PacoGard
- PacoVia
- Pacothane Plus
- Pacoflex

PYRALUX FLEXIBLE MATERIAL DUPONT



- Copper Clad Polyimide Kapton®
- Coverlay – Pyralux® LF/FR
- Bond Sheet – Pyralux® LF/FR
- Adhesiveless – Pyralux® AP
- Interra™ - Embedded Passive
- APR

HDI MATERIALS INTEGRAL TECHNOLOGY INC. (ITI)



- CTE Matched Polyimide Films
- Zeta™ Lam
- Zeta™ Bond
- Zeta™ Cap
- Zeta™ Clad *patent pending

PRODUCTION ASSIST MATERIALS EXPRESS



- Conductive Pastes (CB-100)
- Stencil & Screen Print Materials
- Electrical Test Materials
- PCB & Packaging Tapes
- Lamination Assist Materials
- Photo-Imaging Films & Materials
- Photovoltaic Films & Materials
- Contamination Control Materials
- Drill Room Materials

COPPER FOIL CIRCUIT FOILS & SOMERS



- Electrodeposited
 - Standard & High Performance
 - Double Thin®
 - Double Treat
- Rolled Annealed (RA) Copper with Olin Brass CopperBond®
- Flex Circuit Copper